

Semiconductor Device Physics

Lecture 3

<http://zitompul.wordpress.com>

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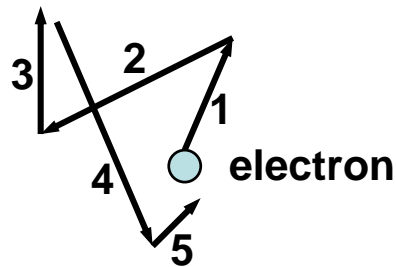
Chapter 3

Carrier Action

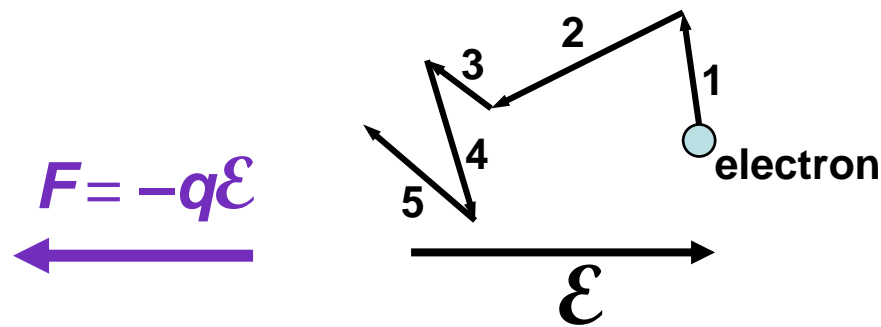
- Three primary types of carrier action occur inside a semiconductor:
 - **Drift:** charged particle motion in response to an applied electric field.
 - **Diffusion:** charged particle motion due to concentration gradient or temperature gradient.
 - **Recombination-Generation:** a process where charge carriers (electrons and holes) are annihilated (destroyed) and created.

Carrier Scattering

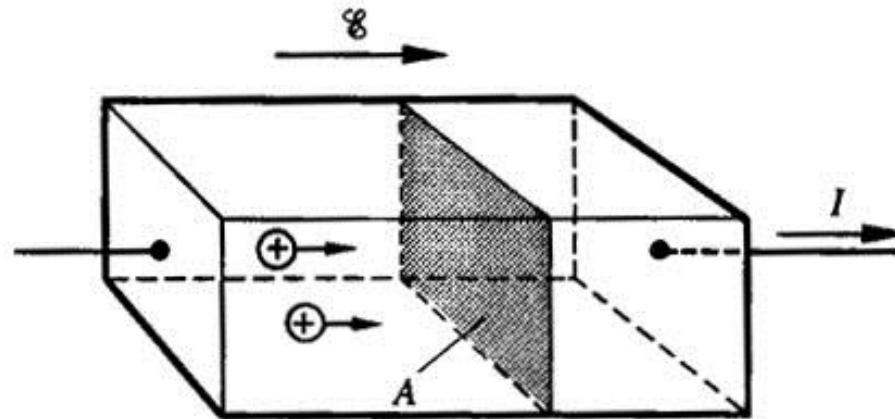
- Mobile electrons and atoms in the Si lattice are always in random thermal motion.
 - Electrons make frequent collisions with the vibrating atoms.
 - “Lattice scattering” or “phonon scattering” increases with increasing temperature.
 - Average velocity of thermal motion for electrons: $\sim 1/1000$ x speed of light at 300 K (even under equilibrium conditions).
- Other scattering mechanisms:
 - Deflection by ionized impurity atoms.
 - Deflection due to Coulombic force between carriers or “carrier-carrier scattering.”
 - Only significant at high carrier concentrations.
- The net current in any direction is zero, if no electric field is applied.



- When an electric field (e.g. due to an externally applied voltage) is applied to a semiconductor, mobile charge-carriers will be accelerated by the electrostatic force.
- This force superimposes on the random motion of electrons.

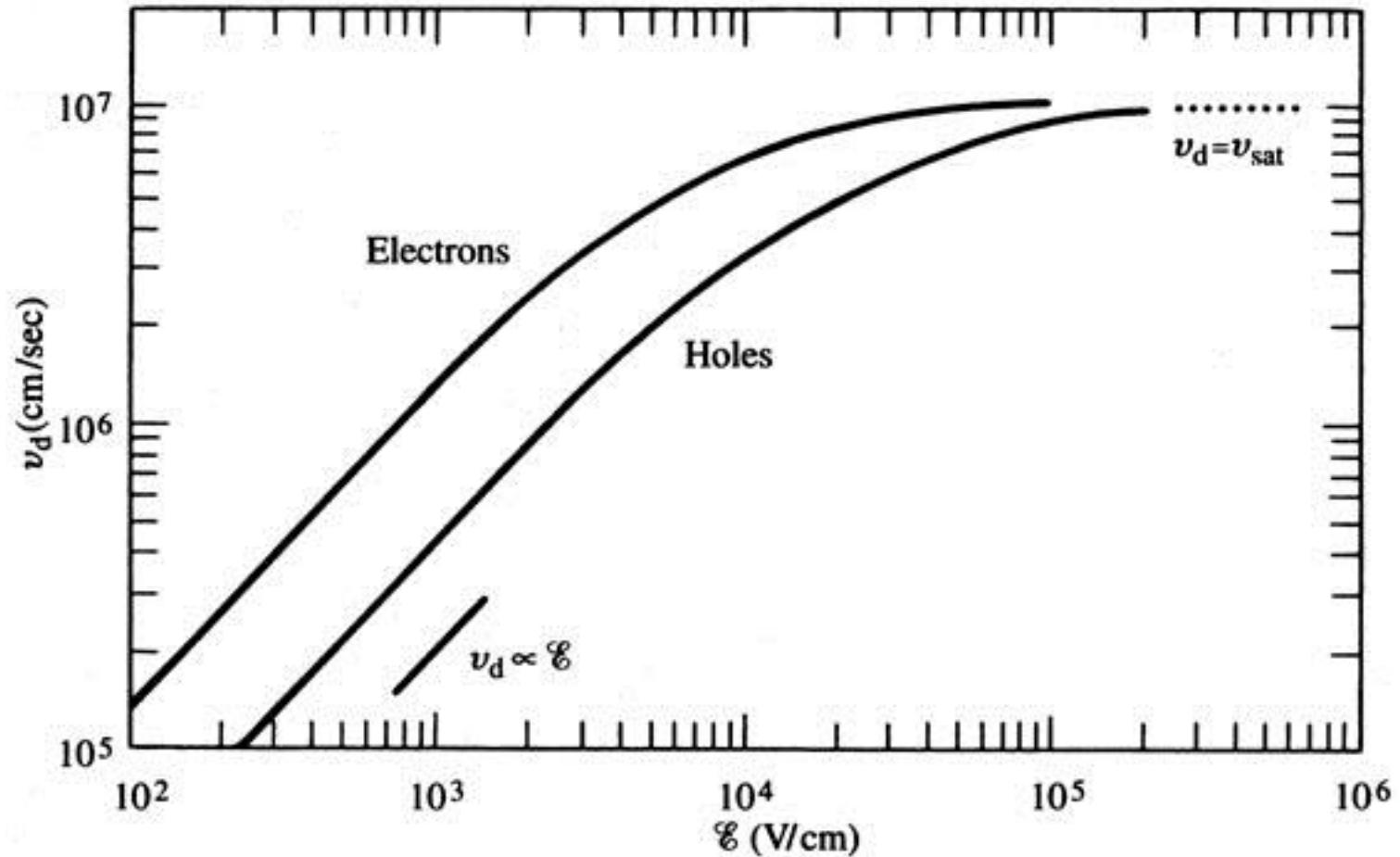


- Electrons drift in the direction opposite to the electric field
 → Current flows.
 - Due to scattering, electrons in a semiconductor do not achieve constant velocity nor acceleration.
 - However, they can be viewed as particles moving at a constant average drift velocity v_d .



- $v_d t$ All holes this distance back from the normal plane will cross the plane in a time t
- $v_d t A$ All holes in this volume will cross the plane in a time t
- $p v_d t A$ Holes crossing the plane in a time t
- $q p v_d t A$ Charge crossing the plane in a time t
- $q p v_d A$ Charge crossing the plane per unit time,
 \Rightarrow Hole drift current $I_{P|drift}$ (Ampere)
- $q p v_d$ Current density associated with hole drift current,
 $\mathbf{J}_{P|drift}$ (A/m²)

Drift Velocity vs. Electric Field



$$v_d = \mu_p \mathcal{E}$$

$$v_d = -\mu_n \mathcal{E}$$

- Linear relation holds in low field intensity, $\sim 5 \times 10^3$ V/cm

Hole and Electron Mobility

μ has the dimensions of v/\mathcal{E} : $\left[\frac{\text{cm/s}}{\text{V/cm}} = \frac{\text{cm}^2}{\text{V} \cdot \text{s}} \right]$

**Electron and hole mobility of selected
intrinsic semiconductors ($T = 300$ K)**

	Si	Ge	GaAs	InAs
μ_n (cm ² /V·s)	1400	3900	8500	30000
μ_p (cm ² /V·s)	470	1900	400	500

Hole and Electron Mobility

■ For holes,

$$I_{P|drift} = qp v_d A$$

$$J_{P|drift} = qp v_d$$

- Hole current due to drift
- Hole current density due to drift

■ In low-field limit,

$$v_d = \mu_p \mathcal{E}$$

$$J_{P|drift} = q \mu_p p \mathcal{E}$$

- μ_p : hole mobility

■ Similarly for electrons,

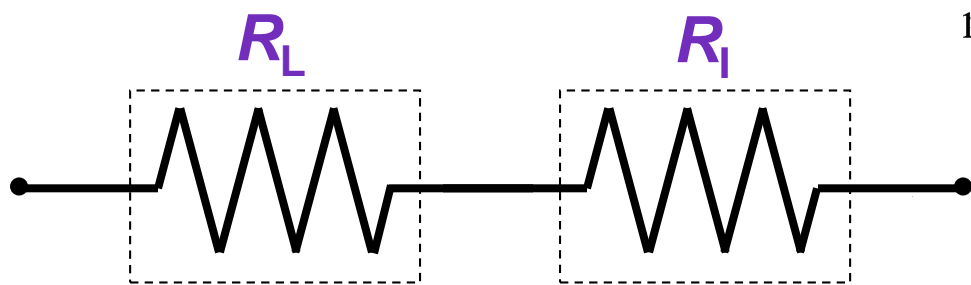
$$J_{N|drift} = -qn v_d$$

$$v_d = -\mu_n \mathcal{E}$$

$$J_{N|drift} = q \mu_n n \mathcal{E}$$

- Electron current density due to drift
- μ_n : electron mobility

Temperature Effect on Mobility

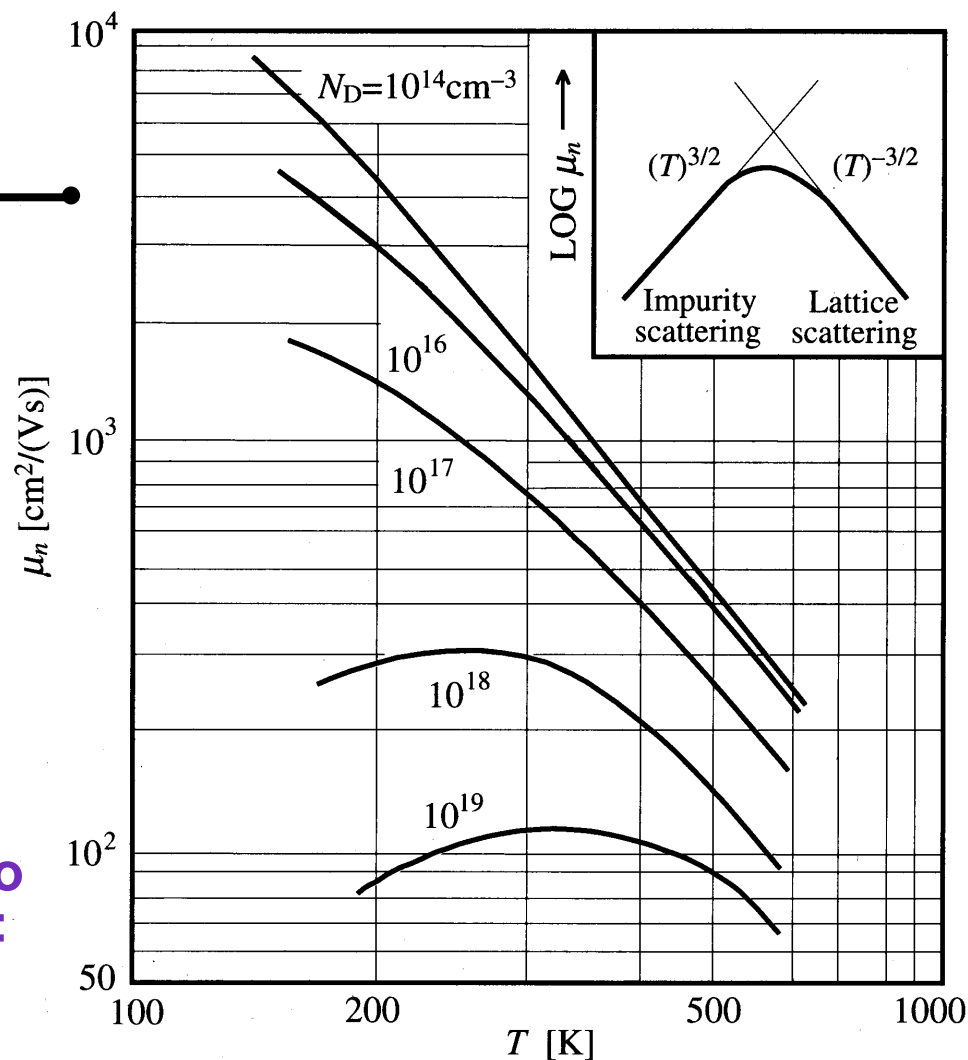


Impedance to motion due to lattice scattering:

- No doping dependence
- Decreases with decreasing temperature

Impedance to motion due to ionized impurity scattering:

- Increases with N_A or N_D
- Increases with decreasing temperature



Temperature Effect on Mobility

- Carrier mobility varies with doping:
 - Decrease with increasing total concentration of ionized dopants.
- Carrier mobility varies with temperature:
 - Decreases with increasing T if lattice scattering is dominant.
 - Decreases with decreasing T if impurity scattering is dominant.

Conductivity and Resistivity

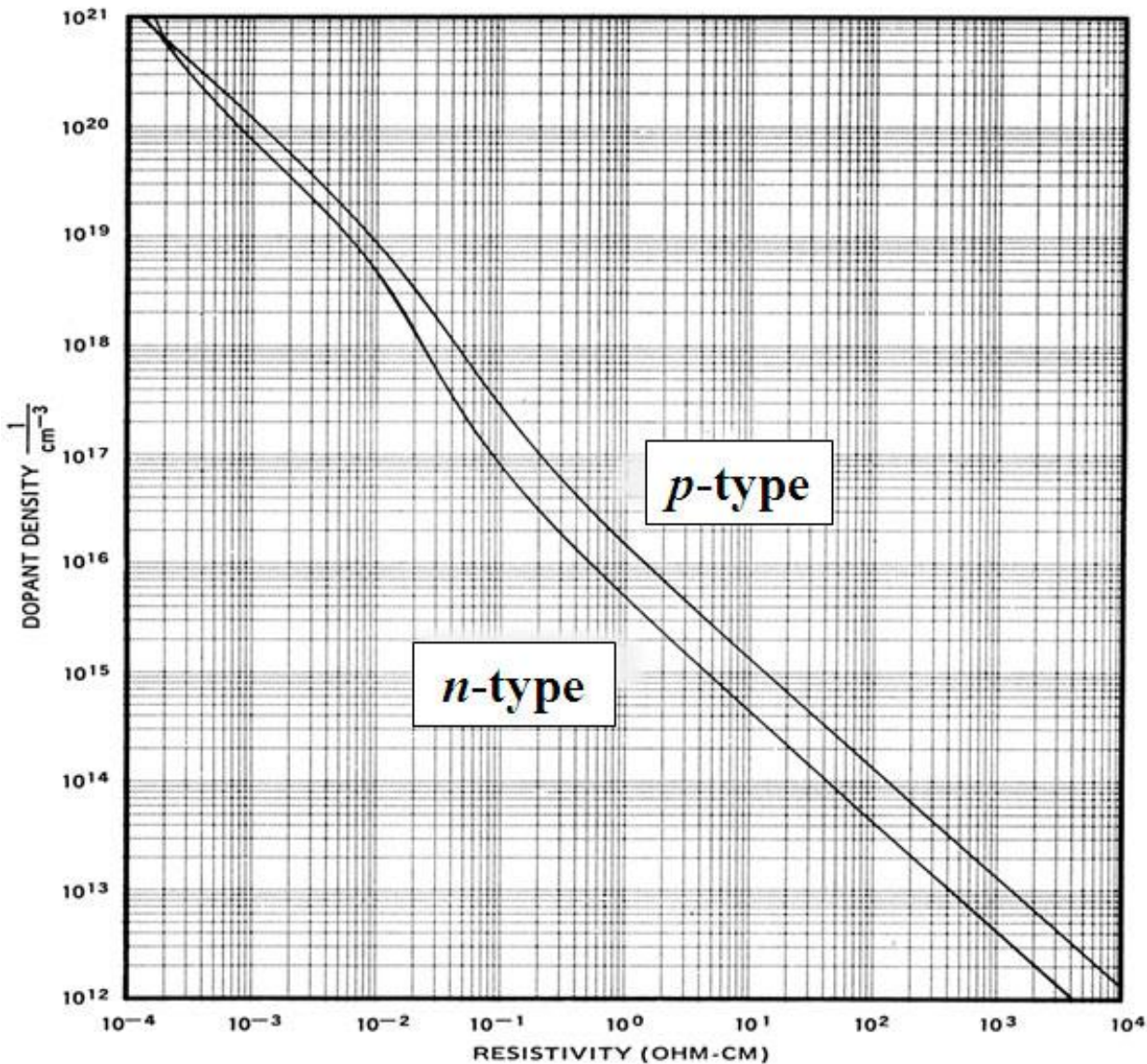
$$\mathbf{J}_{N|\text{drift}} = -qn v_d = q\mu_n n \mathcal{E}$$

$$\mathbf{J}_{P|\text{drift}} = qp v_d = q\mu_p p \mathcal{E}$$

$$\mathbf{J}_{\text{drift}} = \mathbf{J}_{N|\text{drift}} + \mathbf{J}_{P|\text{drift}} = q(\mu_n n + \mu_p p) \mathcal{E} = \sigma \mathcal{E}$$

- **Conductivity** of a semiconductor: $\sigma = q(\mu_n n + \mu_p p)$
- **Resistivity** of a semiconductor: $\rho = 1/\sigma$

Resistivity Dependence on Doping



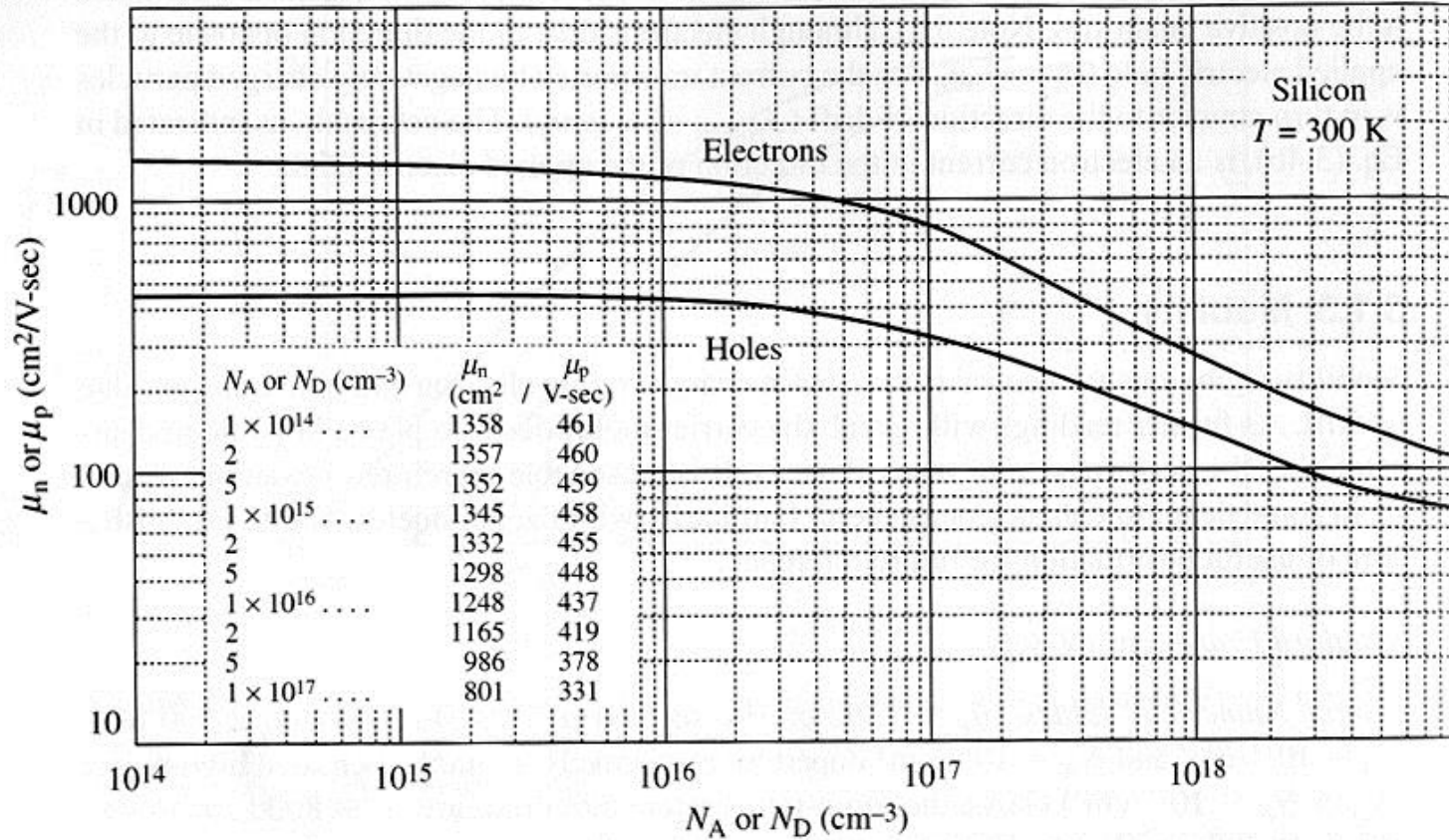
■ For *n*-type material:

$$\rho \cong \frac{1}{q\mu_n N_D}$$

■ For *p*-type material:

$$\rho \cong \frac{1}{q\mu_p N_A}$$

Carrier Mobility as Function Doping Level



Example

- Consider a Si sample at 300 K doped with $10^{16}/\text{cm}^3$ Boron. What is its resistivity?

$$N_A = 10^{16} \text{ cm}^{-3}, N_D = 0$$

$$(N_A \gg N_D \rightarrow p\text{-type})$$

$$p \approx 10^{16} \text{ cm}^{-3}, n \approx 10^4 \text{ cm}^{-3}$$

$$\rho = \frac{1}{q\mu_n n + q\mu_p p}$$

$$\approx \frac{1}{q\mu_p p}$$

$$\approx [(1.6 \times 10^{-19})(437)(10^{16})]^{-1}$$

$$\approx \underline{\underline{1.430 \text{ } \Omega \cdot \text{cm}}}$$

Example

- Consider the same Si sample, doped additionally with $10^{17}/\text{cm}^3$ Arsenic. What is its resistivity now?

$$N_A = 10^{16} \text{ cm}^{-3}, N_D = 10^{17} \text{ cm}^{-3} \quad (N_D > N_A \rightarrow n\text{-type})$$

$$n \approx N_D - N_A = 9 \times 10^{16} \text{ cm}^{-3}, \quad p \approx n_i^2/n = 1.11 \times 10^3 \text{ cm}^{-3}$$

$$\rho = \frac{1}{q\mu_n n + q\mu_p p}$$

$$\approx \frac{1}{q\mu_n n}$$

$$\approx [(1.6 \times 10^{-19})(790)(9 \times 10^{16})]^{-1}$$

$$\approx \underline{\underline{0.0879 \Omega \cdot \text{cm}}}$$

- μ_n is to be taken for the value at $N = N_A + N_D = 1.1 \times 10^{17} \text{ cm}^{-3}$
- $\mu n \approx 790 \text{ cm}^2/\text{V}\cdot\text{s}$

Example

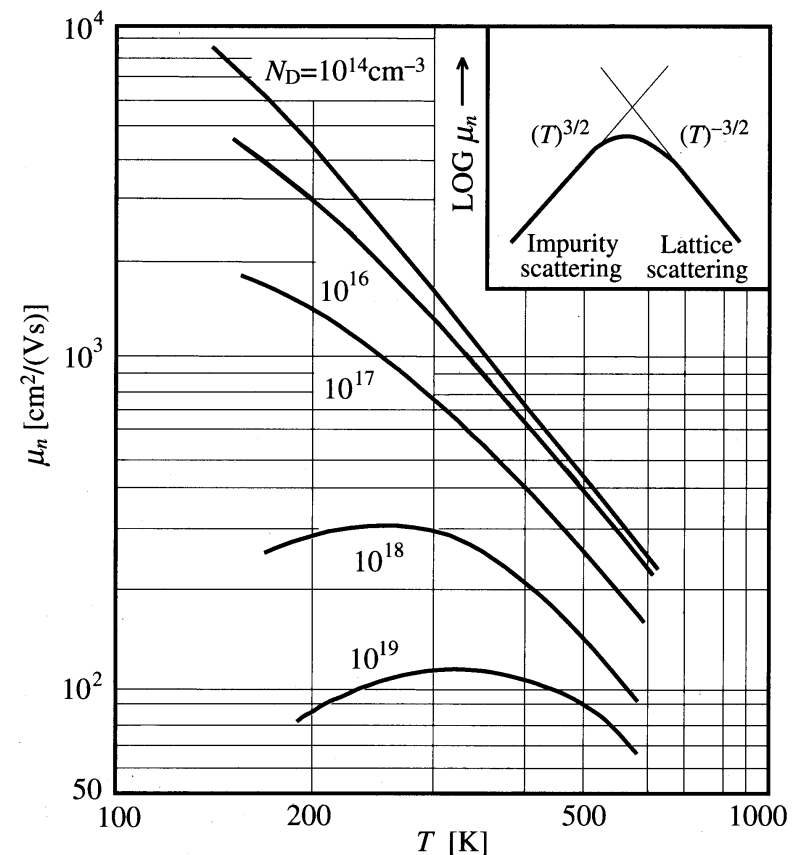
- Consider a Si sample doped with 10^{17}cm^{-3} As. How will its resistivity change when the temperature is increased from $T = 300\text{ K}$ to $T = 400\text{ K}$?

The temperature dependent factor in σ (and therefore ρ) is μ_n .

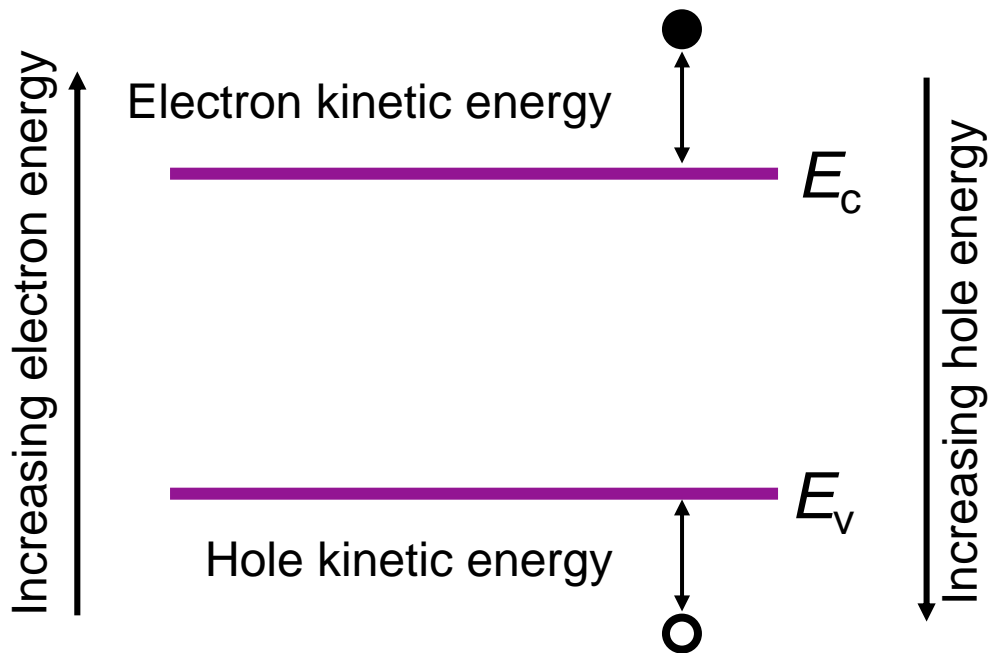
From the mobility vs. temperature curve for 10^{17}cm^{-3} , we find that μ_n decreases from 770 at 300 K to 400 at 400 K.

As a result, ρ **increases** by a factor of:

$$\frac{770}{400} = \underline{\underline{1.93}}$$

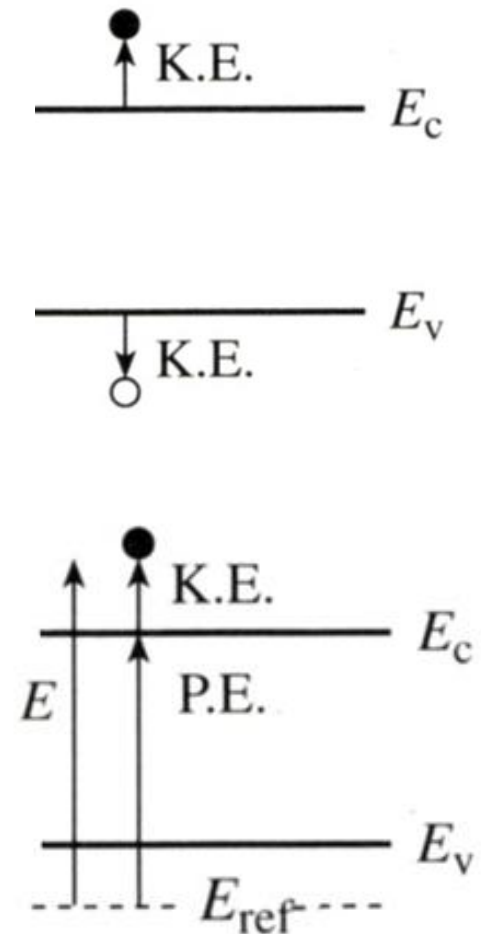


Potential vs. Kinetic Energy



- E_c represents the electron potential energy:

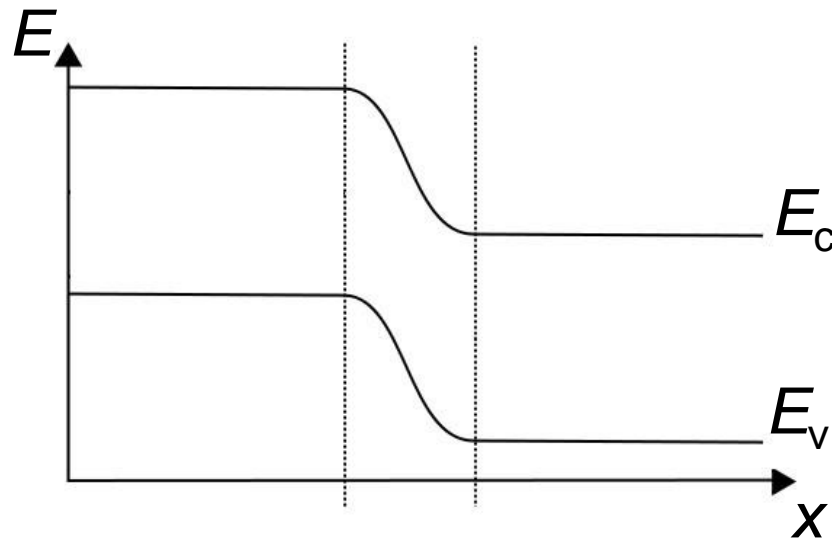
$$\text{P.E.} = E_c - E_{\text{reference}}$$



- E_{ref} is arbitrary

Band Bending

- Until now, E_c and E_v have always been drawn to be independent of the position.
- When an electric field \mathcal{E} exists inside a material, the band energies become a function of position.



- Variation of E_c with position is called “*band bending*”

Band Bending

- The potential energy of a particle with charge $-q$ is related to the electrostatic potential $V(x)$:

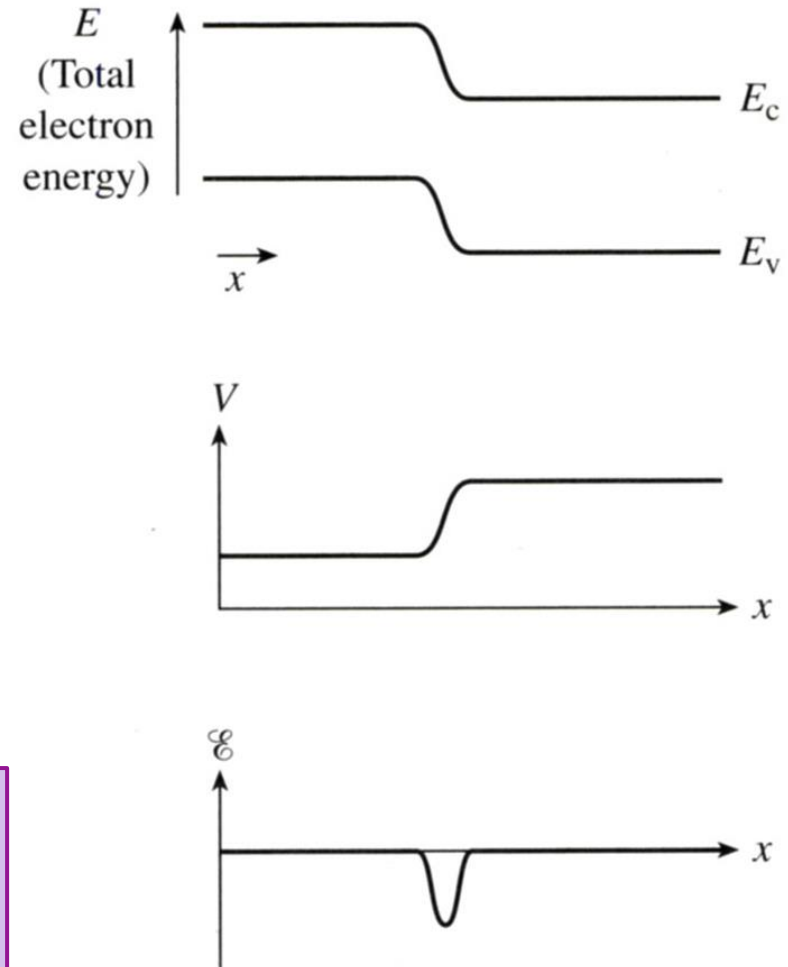
$$\text{P.E.} = -qV$$

$$V = -\frac{1}{q}(E_c - E_{\text{reference}})$$

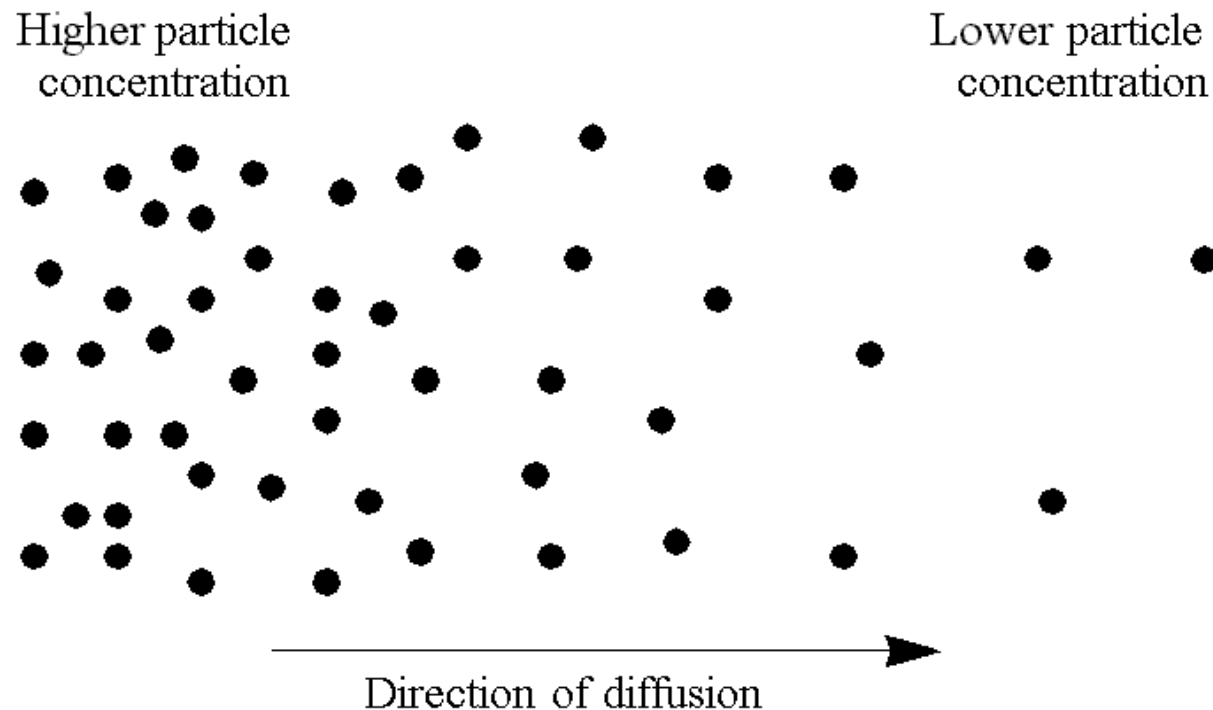
$$\begin{aligned}\mathcal{E} &= -\nabla V \\ &= -\frac{dV}{dx}\end{aligned}$$

$$\mathcal{E} = \frac{1}{q} \frac{dE_c}{dx} = \frac{1}{q} \frac{dE_v}{dx} = \frac{1}{q} \frac{dE_i}{dx}$$

- Since E_c , E_v , and E_i differ only by an additive constant

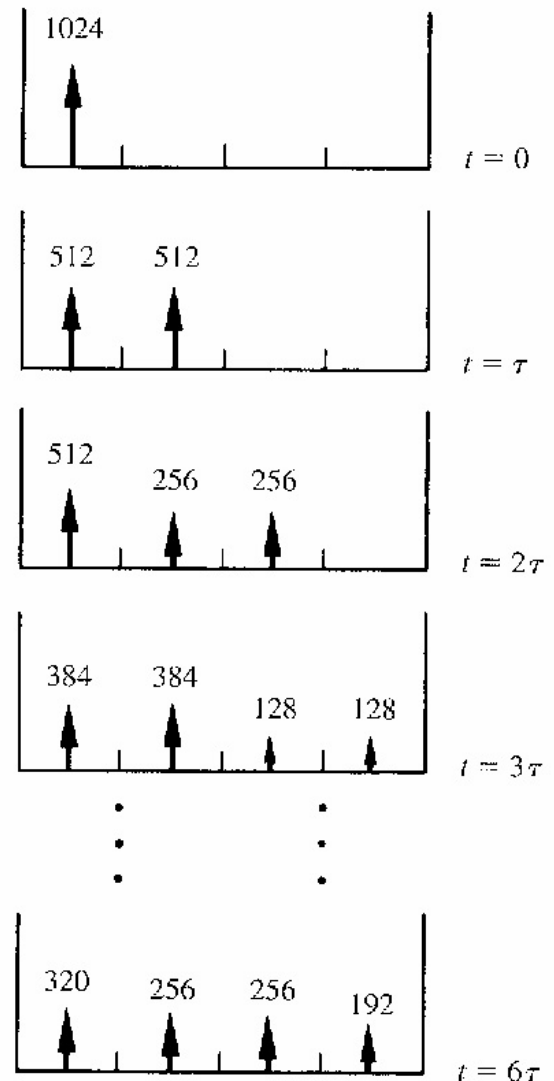


- Particles diffuse from regions of higher concentration to regions of lower concentration region, due to random thermal motion (**Brownian Motion**).



1-D Diffusion Example

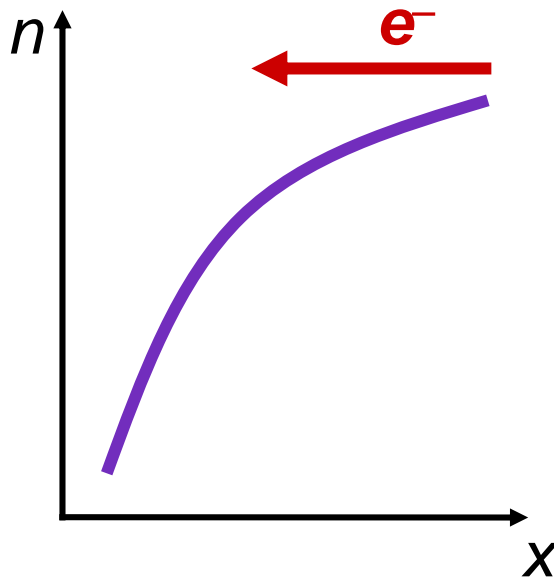
- Thermal motion causes particles to move into an adjacent compartment every τ seconds.



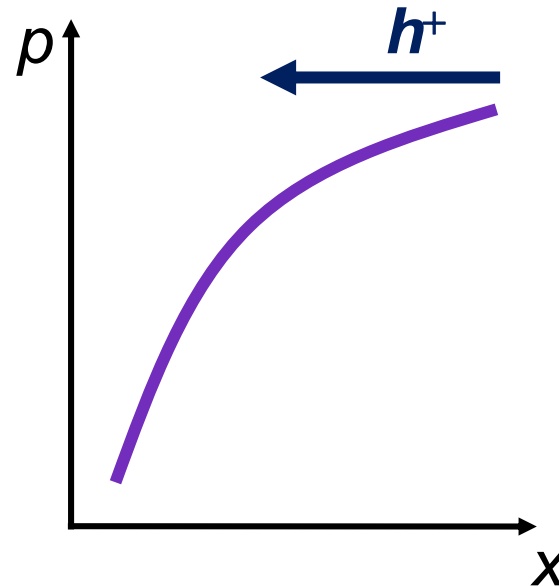
Diffusion Currents

$$\mathbf{J}_{N|\text{diff}} = qD_N \frac{dn}{dx}$$

$$\mathbf{J}_{P|\text{diff}} = -qD_P \frac{dp}{dx}$$



← Electron flow
Current flow →



← Hole flow
← Current flow

- D is the *diffusion coefficient*, in $[\text{cm}^2/\text{sec}]$

Total Currents

$$\mathbf{J} = \mathbf{J}_N + \mathbf{J}_P$$

$$\mathbf{J}_N = \mathbf{J}_{N|\text{drift}} + \mathbf{J}_{N|\text{diff}} = q\mu_n n\mathcal{E} + qD_N \frac{dn}{dx}$$

$$\mathbf{J}_P = \mathbf{J}_{P|\text{drift}} + \mathbf{J}_{P|\text{diff}} = q\mu_p p\mathcal{E} - qD_P \frac{dp}{dx}$$

- **Drift current** flows when an electric field is applied.
- **Diffusion current** flows when a gradient of carrier concentration exist.

Current Flow Under Equilibrium Conditions

- In equilibrium, there is no net flow of electrons or :

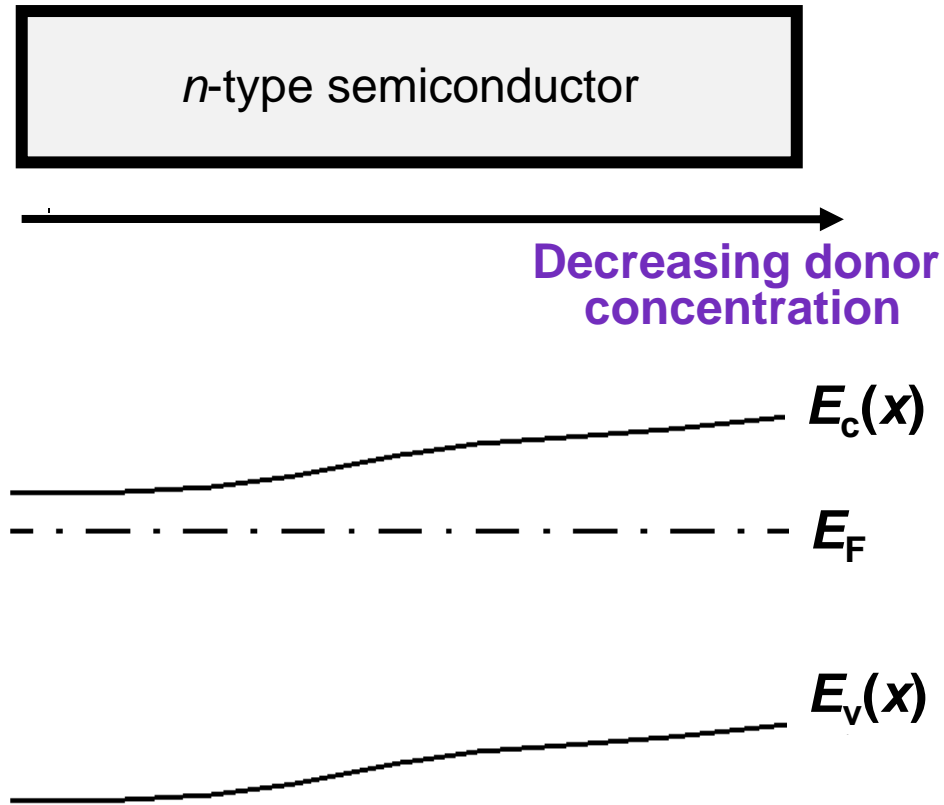
$$\mathbf{J}_N = 0, \quad \mathbf{J}_P = 0$$

- The drift and diffusion current components must balance each other exactly.
- A built-in electric field of ionized atoms exists, such that the drift current exactly cancels out the diffusion current due to the concentration gradient.

$$\mathbf{J}_N = q\mu_n n\mathcal{E} + qD_N \frac{dn}{dx} = 0$$

Current Flow Under Equilibrium Conditions

- Consider a piece of non-uniformly doped semiconductor:



$$n = N_C e^{(E_F - E_c)/kT}$$

$$\frac{dn}{dx} = -\frac{N_C}{kT} e^{(E_F - E_c)/kT} \frac{dE_c}{dx}$$

$$= -\frac{n}{kT} \frac{dE_c}{dx}$$

$$\frac{dn}{dx} = -\frac{q}{kT} n \mathcal{E}$$

- Under equilibrium, E_F inside a material or a group of materials in intimate contact is not a function of position

Einstein Relationship between D and μ

- But, under equilibrium conditions, $\mathbf{J}_N = 0$ and $\mathbf{J}_P = 0$

$$\mathbf{J}_N = q\mu_n n\mathcal{E} + qD_N \frac{dn}{dx} = 0$$

$$qn\mathcal{E}\mu_n - qn\mathcal{E} \frac{q}{kT} D_N = 0 \longrightarrow$$

$$\frac{D_N}{\mu_n} = \frac{kT}{q}$$

Similarly,

$$\frac{D_P}{\mu_p} = \frac{kT}{q}$$

• Einstein Relationship

- Further proof can show that the **Einstein Relationship** is valid for a non-degenerate semiconductor, both in equilibrium and non-equilibrium conditions.

Example: Diffusion Coefficient

- What is the hole diffusion coefficient in a sample of silicon at 300 K with $\mu_p = 410 \text{ cm}^2 / \text{V}\cdot\text{s}$?

$$\begin{aligned}
 D_p &= \left(\frac{kT}{q} \right) \mu_p \\
 &= \frac{25.86 \text{ meV}}{1 \text{ e}} \cdot 410 \text{ cm}^2 \text{V}^{-1} \text{s}^{-1} \\
 &= 25.86 \text{ mV} \cdot 410 \frac{\text{cm}^2}{\text{V} \cdot \text{s}} \\
 &= \underline{\underline{10.603 \text{ cm}^2/\text{s}}}
 \end{aligned}$$

$$\frac{1 \text{ eV}}{1 \text{ e}} = 1 \text{ V}$$

$$1 \text{ eV} = 1.602 \times 10^{-19} \text{ J}$$

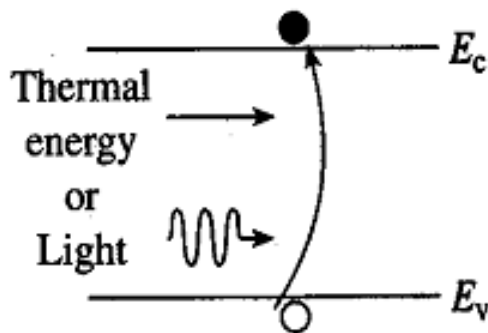
- Remark:** $kT/q = 25.86 \text{ mV}$ at room temperature

Recombination–Generation

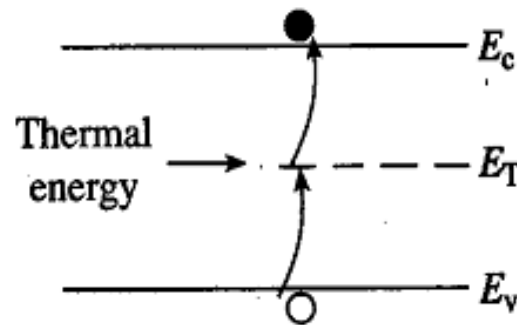
- **Recombination:** a process by which conduction electrons and holes are annihilated in pairs.
- **Generation:** a process by which conduction electrons and holes are created in pairs.
- Generation and recombination processes act to change the carrier concentrations, and thereby indirectly affect current flow.

Generation Processes

Band-to-Band



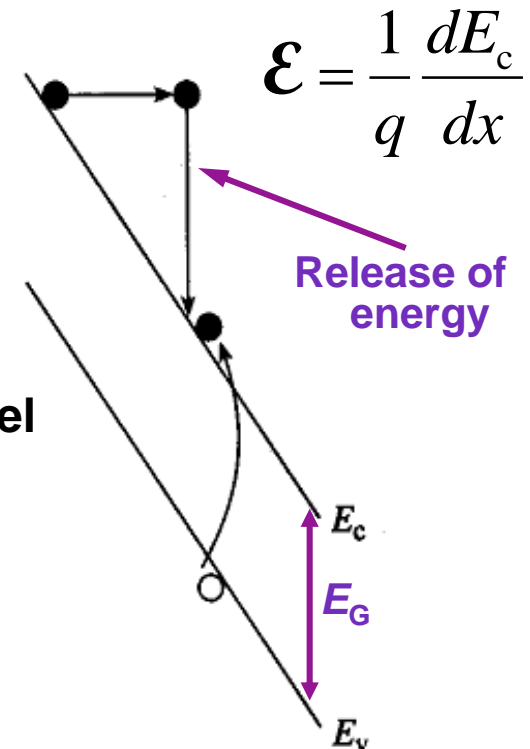
R-G Center



E_T : trap energy level

- Due to lattice defects or unintentional impurities
- Also called indirect generation

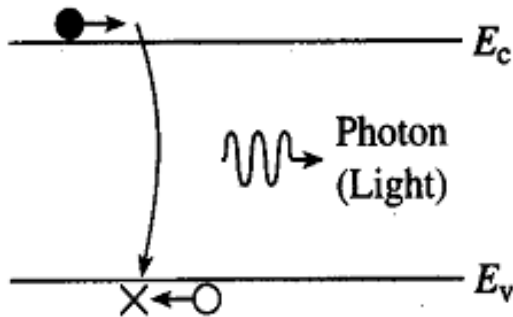
Impact Ionization



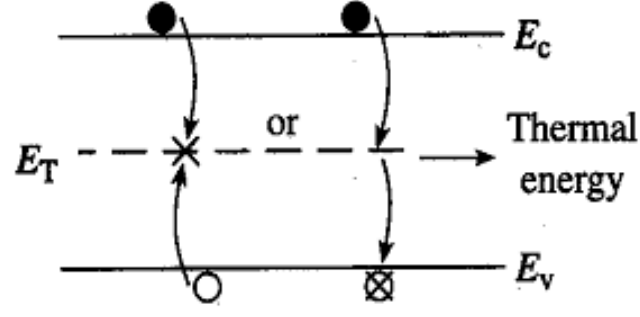
- Only occurs in the presence of large \mathcal{E}

Recombination Processes

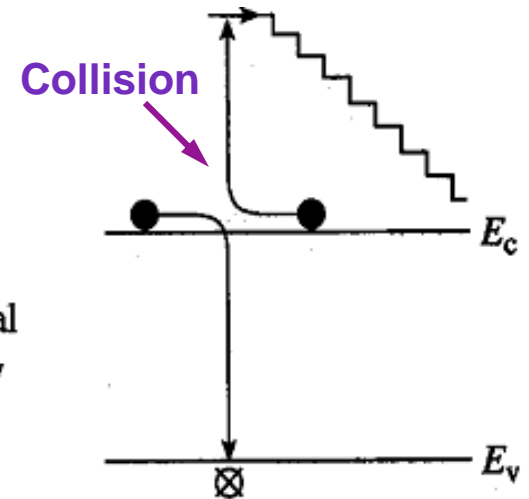
Band-to-Band



R-G Center



Auger



- Rate is limited by minority carrier trapping
- Primary recombination way for Si

- Occurs in heavily doped material

- 1. (4.17)
Problem 3.6, Pierret's "Semiconductor Device Fundamentals".
- 2. (4.27)
Problem 3.12, from (a) until (f), for Figure P3.12(a) and Figure P3.12(f), Pierret's "Semiconductor Device Fundamentals".
- 3. (5.28)
The electron concentration in silicon at $T = 300$ K is given by

$$n(x) = 10^{16} \exp\left(\frac{-x}{18}\right) \text{cm}^{-3}$$

where x is measured in μm and is limited to $0 \leq x \leq 25 \mu\text{m}$. The electron diffusion coefficient is $D_N = 25 \text{ cm}^2/\text{s}$ and the electron mobility is $\mu_n = 960 \text{ cm}^2/(\text{Vs})$. The total electron current density through the semiconductor is constant and equal to $\mathbf{J}_N = -40 \text{ A/cm}^2$. The electron current has both diffusion and drift current components.

Determine the electric field as a function of x which must exist in the semiconductor. Sketch the function.